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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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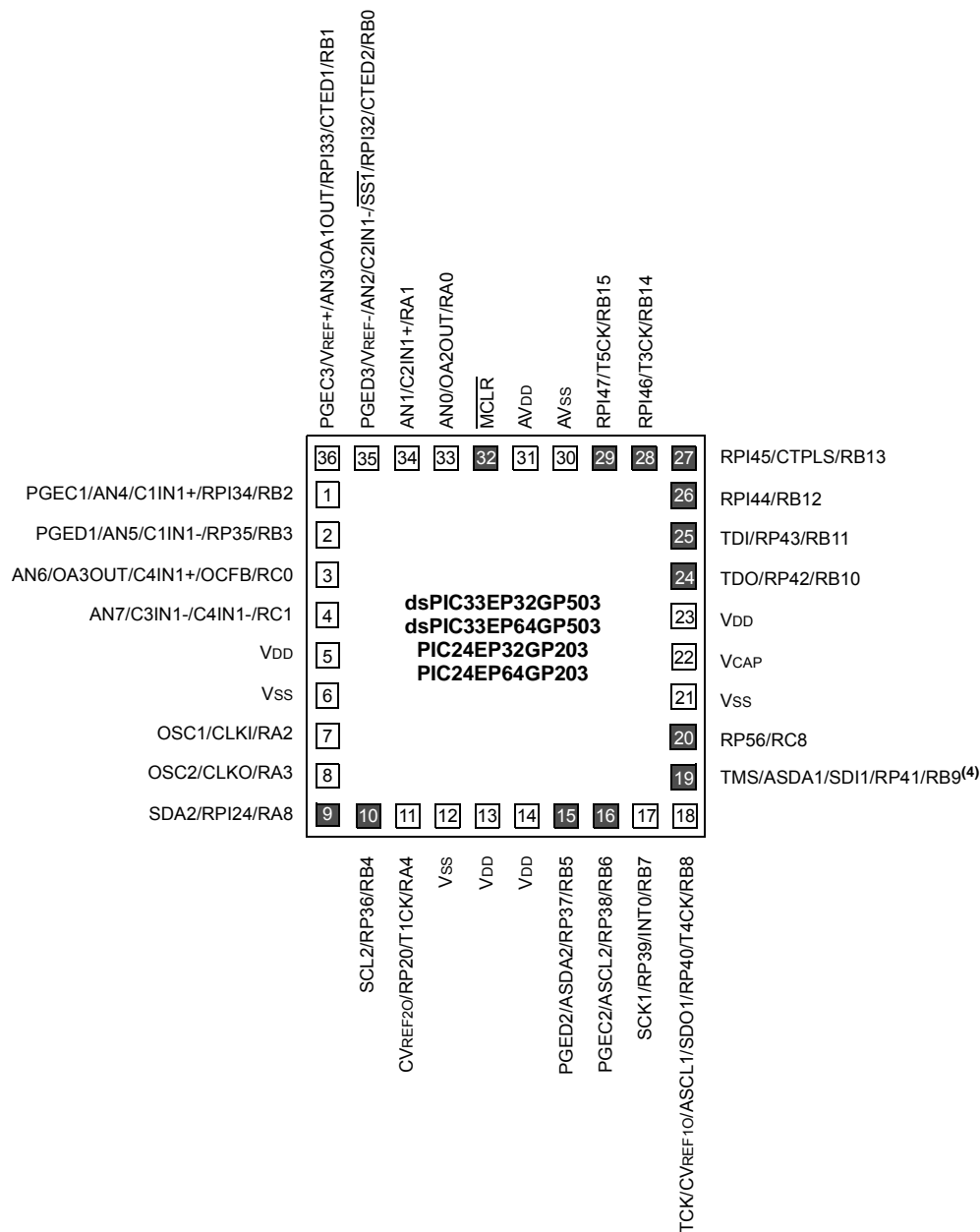
Details

Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32mc502t-e-mm

Pin Diagrams (Continued)

36-Pin VTLA^(1,2,3)

■ = Pins are up to 5V tolerant



- Note**
- 1: The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
 - 2: Every I/O port pin (RAX-RGx) can be used as a Change Notification pin (CNAX-CNGx). See **Section 11.0 “I/O Ports”** for more information.
 - 3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
 - 4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 2-5: SINGLE-PHASE SYNCHRONOUS BUCK CONVERTER

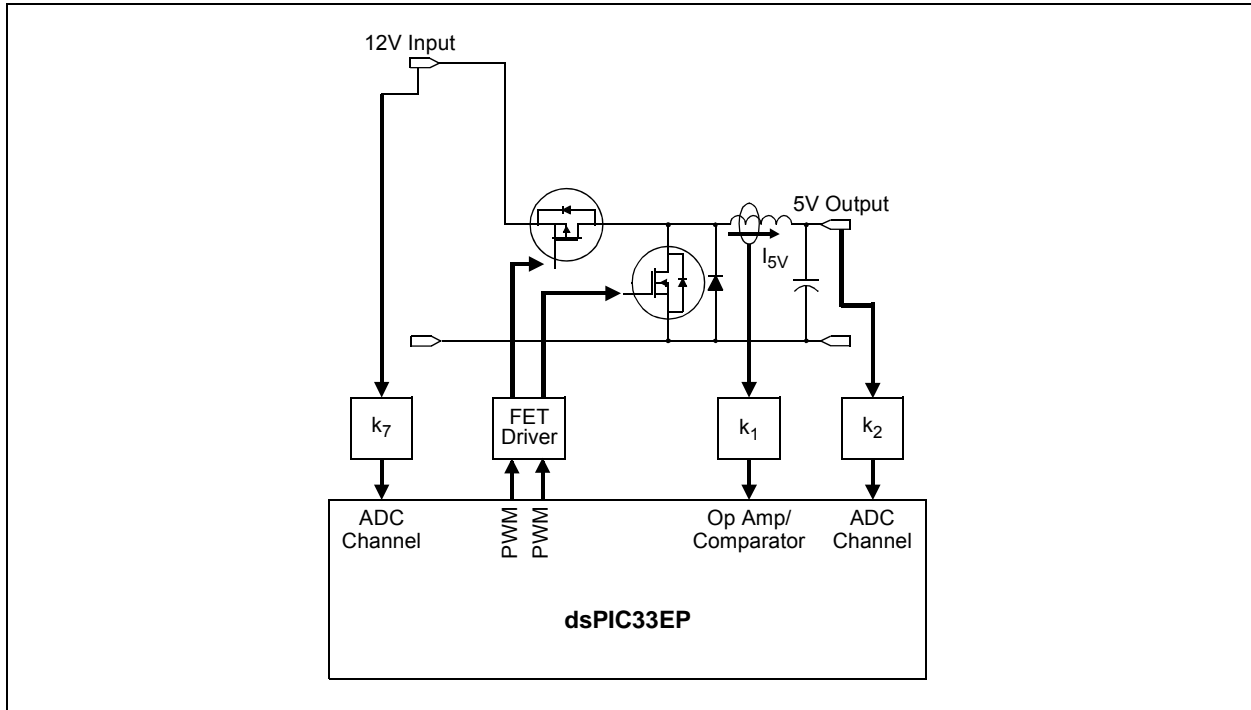
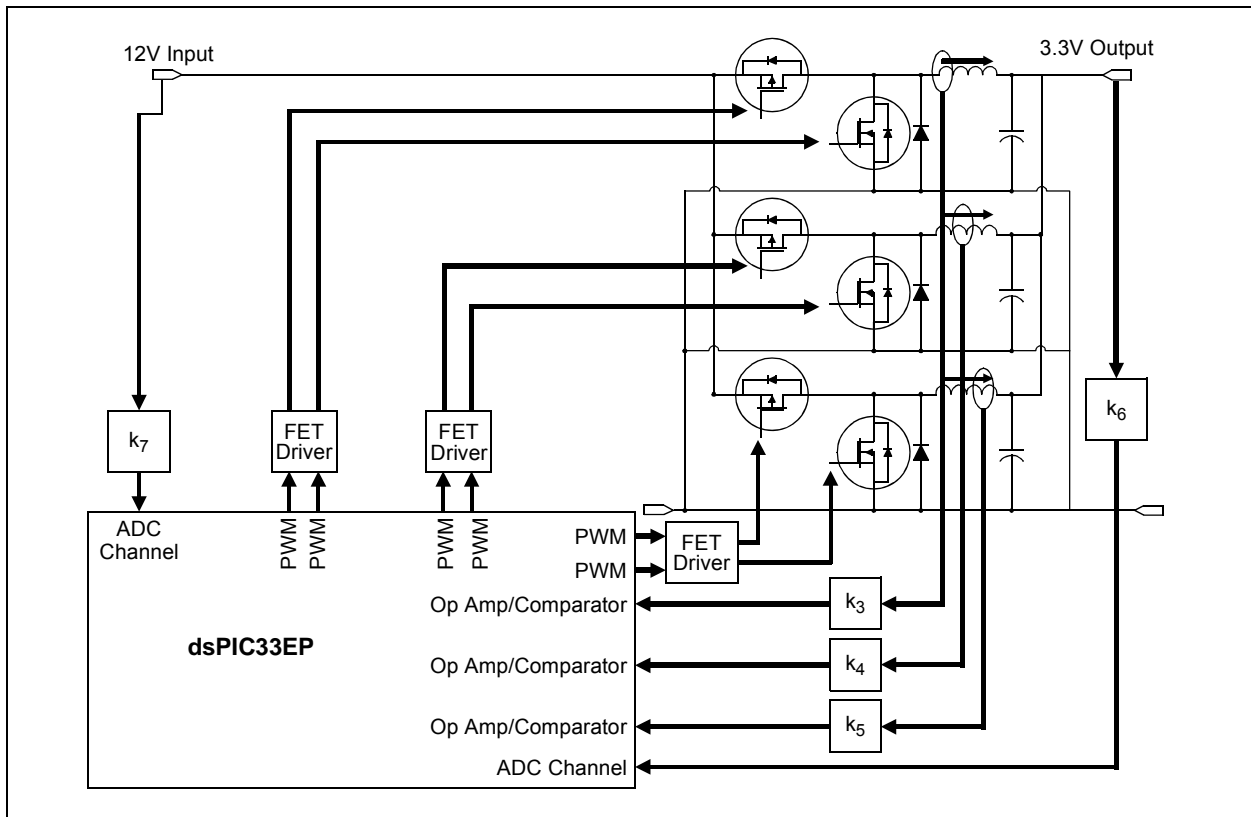


FIGURE 2-6: MULTIPHASE SYNCHRONOUS BUCK CONVERTER

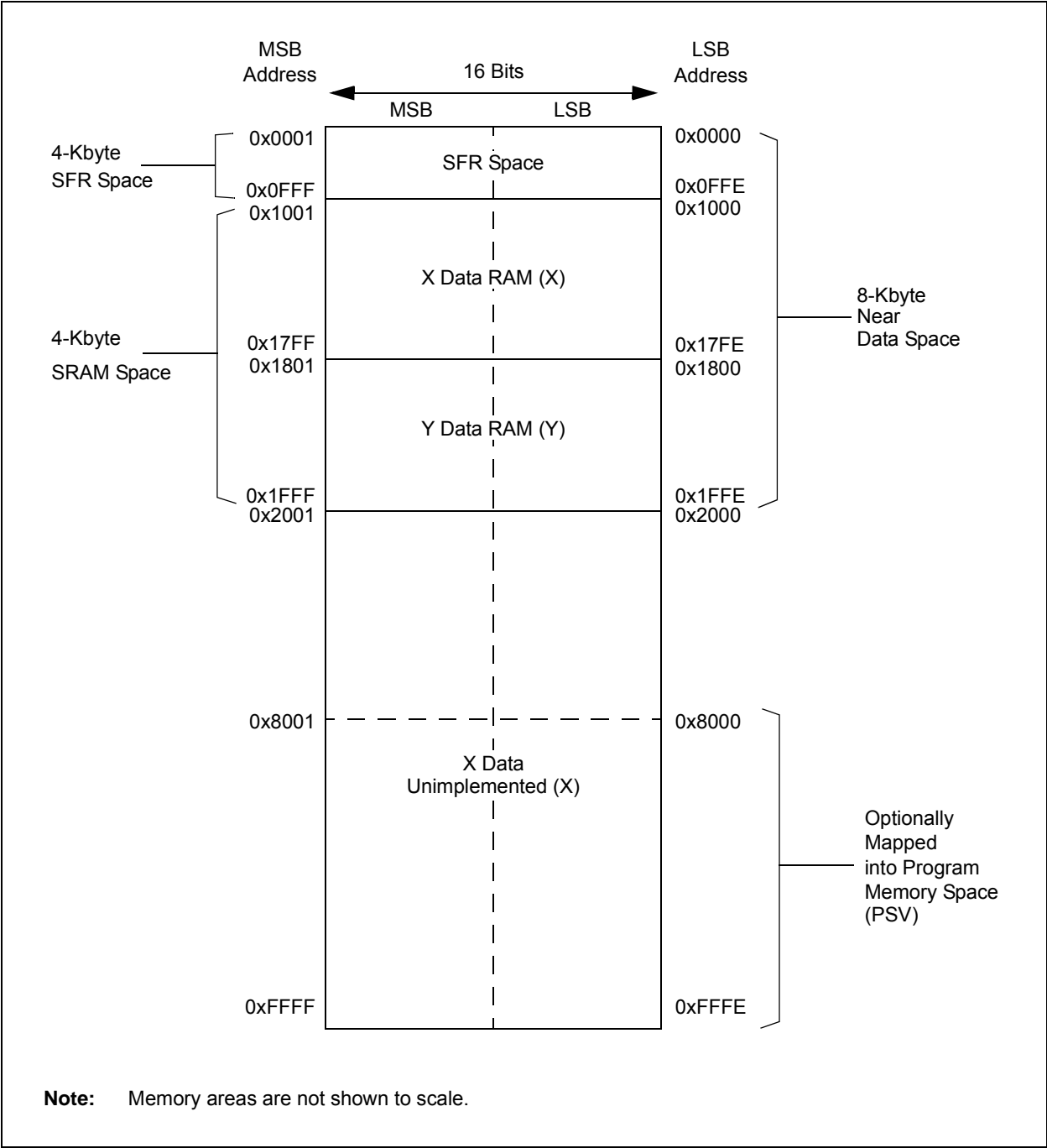


REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5	IPL<2:0> : CPU Interrupt Priority Level Status bits ^(2,3) 111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled 110 = CPU Interrupt Priority Level is 6 (14) 101 = CPU Interrupt Priority Level is 5 (13) 100 = CPU Interrupt Priority Level is 4 (12) 011 = CPU Interrupt Priority Level is 3 (11) 010 = CPU Interrupt Priority Level is 2 (10) 001 = CPU Interrupt Priority Level is 1 (9) 000 = CPU Interrupt Priority Level is 0 (8)
bit 4	RA : REPEAT Loop Active bit 1 = REPEAT loop in progress 0 = REPEAT loop not in progress
bit 3	N : MCU ALU Negative bit 1 = Result was negative 0 = Result was non-negative (zero or positive)
bit 2	OV : MCU ALU Overflow bit This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude that causes the sign bit to change state. 1 = Overflow occurred for signed arithmetic (in this arithmetic operation) 0 = No overflow occurred
bit 1	Z : MCU ALU Zero bit 1 = An operation that affects the Z bit has set it at some time in the past 0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)
bit 0	C : MCU ALU Carry/Borrow bit 1 = A carry-out from the Most Significant bit of the result occurred 0 = No carry-out from the Most Significant bit of the result occurred

- Note 1:** This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.
- 2:** The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
- 3:** The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.
- 4:** A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

FIGURE 4-7: DATA MEMORY MAP FOR dsPIC33EP32MC20X/50X AND dsPIC33EP32GP50X DEVICES



REGISTER 11-6: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
—	OCFAR<6:0>							
bit 7								bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-0 **OCFAR<6:0>:** Assign Output Compare Fault A (OCFA) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121

.

.

.

0000001 = Input tied to CMP1

0000000 = Input tied to Vss

REGISTER 11-8: RPINR14: PERIPHERAL PIN SELECT INPUT REGISTER 14
(dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEB1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEA1R<6:0>						
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **QEB1R<6:0>:** Assign B (QEB) to the Corresponding RPn Pin bits
 (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121

.

.

.

0000001 = Input tied to CMP1

0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **QEA1R<6:0>:** Assign A (QEA) to the Corresponding RPn Pin bits
 (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121

.

.

.

0000001 = Input tied to CMP1

0000000 = Input tied to Vss

REGISTER 16-2: PTCON2: PWMx PRIMARY MASTER CLOCK DIVIDER SELECT REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PCLKDIV2 ⁽¹⁾	PCLKDIV1 ⁽¹⁾	PCLKDIV0 ⁽¹⁾
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-3 **Unimplemented:** Read as '0'

bit 2-0 **PCLKDIV<2:0>:** PWMx Input Clock Prescaler (Divider) Select bits⁽¹⁾

111 = Reserved

110 = Divide-by-64

101 = Divide-by-32

100 = Divide-by-16

011 = Divide-by-8

010 = Divide-by-4

001 = Divide-by-2

000 = Divide-by-1, maximum PWMx timing resolution (power-on default)

Note 1: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

REGISTER 21-13: CxBUFNT2: ECANx FILTER 4-7 BUFFER POINTER REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F7BP<3:0>				F6BP<3:0>			
bit 15				bit 8			
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F5BP<3:0>				F4BP<3:0>			
bit 7				bit 0			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-12 **F7BP<3:0>**: RX Buffer Mask for Filter 7 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0
- bit 11-8 **F6BP<3:0>**: RX Buffer Mask for Filter 6 bits (same values as bits<15:12>)
- bit 7-4 **F5BP<3:0>**: RX Buffer Mask for Filter 5 bits (same values as bits<15:12>)
- bit 3-0 **F4BP<3:0>**: RX Buffer Mask for Filter 4 bits (same values as bits<15:12>)

REGISTER 21-14: CxBUFNT3: ECANx FILTER 8-11 BUFFER POINTER REGISTER 3

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11BP<3:0>				F10BP<3:0>			
bit 15				bit 8			
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F9BP<3:0>				F8BP<3:0>			
bit 7				bit 0			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-12 **F11BP<3:0>**: RX Buffer Mask for Filter 11 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0
- bit 11-8 **F10BP<3:0>**: RX Buffer Mask for Filter 10 bits (same values as bits<15:12>)
- bit 7-4 **F9BP<3:0>**: RX Buffer Mask for Filter 9 bits (same values as bits<15:12>)
- bit 3-0 **F8BP<3:0>**: RX Buffer Mask for Filter 8 bits (same values as bits<15:12>)

REGISTER 21-19: CxFMSKSEL2: ECANx FILTER 15-8 MASK SELECTION REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-14 **F15MSK<1:0>**: Mask Source for Filter 15 bits
 11 = Reserved
 10 = Acceptance Mask 2 registers contain mask
 01 = Acceptance Mask 1 registers contain mask
 00 = Acceptance Mask 0 registers contain mask
- bit 13-12 **F14MSK<1:0>**: Mask Source for Filter 14 bits (same values as bits<15:14>)
- bit 11-10 **F13MSK<1:0>**: Mask Source for Filter 13 bits (same values as bits<15:14>)
- bit 9-8 **F12MSK<1:0>**: Mask Source for Filter 12 bits (same values as bits<15:14>)
- bit 7-6 **F11MSK<1:0>**: Mask Source for Filter 11 bits (same values as bits<15:14>)
- bit 5-4 **F10MSK<1:0>**: Mask Source for Filter 10 bits (same values as bits<15:14>)
- bit 3-2 **F9MSK<1:0>**: Mask Source for Filter 9 bits (same values as bits<15:14>)
- bit 1-0 **F8MSK<1:0>**: Mask Source for Filter 8 bits (same values as bits<15:14>)

BUFFER 21-3: ECAN™ MESSAGE BUFFER WORD 2

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID5	EID4	EID3	EID2	EID1	EID0	RTR	RB1
bit 15							bit 8

U-x	U-x	U-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	RB0	DLC3	DLC2	DLC1	DLC0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15-10 **EID<5:0>**: Extended Identifier bits
- bit 9 **RTR**: Remote Transmission Request bit
 When IDE = 1:
 1 = Message will request remote transmission
 0 = Normal message
 When IDE = 0:
 The RTR bit is ignored.
- bit 8 **RB1**: Reserved Bit 1
 User must set this bit to '0' per CAN protocol.
- bit 7-5 **Unimplemented**: Read as '0'
- bit 4 **RB0**: Reserved Bit 0
 User must set this bit to '0' per CAN protocol.
- bit 3-0 **DLC<3:0>**: Data Length Code bits

BUFFER 21-4: ECAN™ MESSAGE BUFFER WORD 3

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 1							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 0							
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15-8 **Byte 1<15:8>**: ECAN Message Byte 1 bits
- bit 7-0 **Byte 0<7:0>**: ECAN Message Byte 0 bits

REGISTER 23-6: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB	—	—	CH0SB4 ⁽¹⁾	CH0SB3 ⁽¹⁾	CH0SB2 ⁽¹⁾	CH0SB1 ⁽¹⁾	CH0SB0 ⁽¹⁾
bit 15							bit 8

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA	—	—	CH0SA4 ⁽¹⁾	CH0SA3 ⁽¹⁾	CH0SA2 ⁽¹⁾	CH0SA1 ⁽¹⁾	CH0SA0 ⁽¹⁾
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15 **CH0NB:** Channel 0 Negative Input Select for Sample MUXB bit
 1 = Channel 0 negative input is AN1⁽¹⁾
 0 = Channel 0 negative input is VREFL
- bit 14-13 **Unimplemented:** Read as '0'
- bit 12-8 **CH0SB<4:0>:** Channel 0 Positive Input Select for Sample MUXB bits⁽¹⁾
 11111 = Open; use this selection with CTMU capacitive and time measurement
 11110 = Channel 0 positive input is connected to the CTMU temperature measurement diode (CTMU TEMP)
 11101 = Reserved
 11100 = Reserved
 11011 = Reserved
 11010 = Channel 0 positive input is the output of OA3/AN6^(2,3)
 11001 = Channel 0 positive input is the output of OA2/AN0⁽²⁾
 11000 = Channel 0 positive input is the output of OA1/AN3⁽²⁾
 10111 = Reserved
 •
 •
 •
 10000 = Reserved
 01111 = Channel 0 positive input is AN15⁽³⁾
 01110 = Channel 0 positive input is AN14⁽³⁾
 01101 = Channel 0 positive input is AN13⁽³⁾
 •
 •
 •
 00010 = Channel 0 positive input is AN2⁽³⁾
 00001 = Channel 0 positive input is AN1⁽³⁾
 00000 = Channel 0 positive input is AN0⁽³⁾
- bit 7 **CH0NA:** Channel 0 Negative Input Select for Sample MUXA bit
 1 = Channel 0 negative input is AN1⁽¹⁾
 0 = Channel 0 negative input is VREFL
- bit 6-5 **Unimplemented:** Read as '0'

- Note 1:** AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.
- 2:** The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.
- 3:** See the “Pin Diagrams” section for the available analog channels for each device.

REGISTER 27-1: DEVID: DEVICE ID REGISTER

R	R	R	R	R	R	R	R
DEVID<23:16> ⁽¹⁾							
bit 23				bit 16			

R	R	R	R	R	R	R	R
DEVID<15:8> ⁽¹⁾							
bit 15				bit 8			

R	R	R	R	R	R	R	R
DEVID<7:0> ⁽¹⁾							
bit 7				bit 0			

Legend: R = Read-Only bit U = Unimplemented bit

bit 23-0 **DEVID<23:0>:** Device Identifier bits⁽¹⁾

Note 1: Refer to the “dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits” (DS70663) for the list of device ID values.

REGISTER 27-2: DEVREV: DEVICE REVISION REGISTER

R	R	R	R	R	R	R	R
DEVREV<23:16> ⁽¹⁾							
bit 23				bit 16			

R	R	R	R	R	R	R	R
DEVREV<15:8> ⁽¹⁾							
bit 15				bit 8			

R	R	R	R	R	R	R	R
DEVREV<7:0> ⁽¹⁾							
bit 7				bit 0			

Legend: R = Read-only bit U = Unimplemented bit

bit 23-0 **DEVREV<23:0>:** Device Revision bits⁽¹⁾

Note 1: Refer to the “dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits” (DS70663) for the list of device revision values.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected
53	NEG	NEG $Acc^{(1)}$	Negate Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
		NEG f	$f = \bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG $f, WREG$	$WREG = \bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG Ws, Wd	$Wd = \bar{Ws} + 1$	1	1	C,DC,N,OV,Z
54	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
55	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to $W(nd):W(nd + 1)$	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
56	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push $W(ns):W(ns + 1)$ to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
57	PWRSV	PWRSV $\#lit1$	Go into Sleep or Idle mode	1	1	WDTO,Sleep
58	RCALL	RCALL $Expr$	Relative Call	1	4	SFA
		RCALL Wn	Computed Call	1	4	SFA
59	REPEAT	REPEAT $\#lit15$	Repeat Next Instruction $lit15 + 1$ times	1	1	None
		REPEAT Wn	Repeat Next Instruction $(Wn) + 1$ times	1	1	None
60	RESET	RESET	Software device Reset	1	1	None
61	RETFIE	RETFIE	Return from interrupt	1	6 (5)	SFA
62	RETLW	RETLW $\#lit10, Wn$	Return with literal in Wn	1	6 (5)	SFA
63	RETURN	RETURN	Return from Subroutine	1	6 (5)	SFA
64	RLC	RLC f	$f = \text{Rotate Left through Carry } f$	1	1	C,N,Z
		RLC $f, WREG$	$WREG = \text{Rotate Left through Carry } f$	1	1	C,N,Z
		RLC Ws, Wd	$Wd = \text{Rotate Left through Carry } Ws$	1	1	C,N,Z
65	RLNC	RLNC f	$f = \text{Rotate Left (No Carry) } f$	1	1	N,Z
		RLNC $f, WREG$	$WREG = \text{Rotate Left (No Carry) } f$	1	1	N,Z
		RLNC Ws, Wd	$Wd = \text{Rotate Left (No Carry) } Ws$	1	1	N,Z
66	RRC	RRC f	$f = \text{Rotate Right through Carry } f$	1	1	C,N,Z
		RRC $f, WREG$	$WREG = \text{Rotate Right through Carry } f$	1	1	C,N,Z
		RRC Ws, Wd	$Wd = \text{Rotate Right through Carry } Ws$	1	1	C,N,Z
67	RRNC	RRNC f	$f = \text{Rotate Right (No Carry) } f$	1	1	N,Z
		RRNC $f, WREG$	$WREG = \text{Rotate Right (No Carry) } f$	1	1	N,Z
		RRNC Ws, Wd	$Wd = \text{Rotate Right (No Carry) } Ws$	1	1	N,Z
68	SAC	SAC $Acc, \#Slit4, Wdo^{(1)}$	Store Accumulator	1	1	None
		SAC.R $Acc, \#Slit4, Wdo^{(1)}$	Store Rounded Accumulator	1	1	None
69	SE	SE Ws, Wnd	$Wnd = \text{sign-extended } Ws$	1	1	C,N,Z
70	SETM	SETM f	$f = 0xFFFF$	1	1	None
		SETM $WREG$	$WREG = 0xFFFF$	1	1	None
		SETM Ws	$Ws = 0xFFFF$	1	1	None
71	SFTAC	SFTAC $Acc, Wn^{(1)}$	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB,SA,SB,SAB
		SFTAC $Acc, \#Slit6^{(1)}$	Arithmetic Shift Accumulator by $Slit6$	1	1	OA,OB,OAB,SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

29.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
 - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB XC Compiler
 - MPASM™ Assembler
 - MPLINK™ Object Linker/
MPLIB™ Object Librarian
 - MPLAB Assembler/Linker/Librarian for
Various Device Families
- Simulators
 - MPLAB X SIM Software Simulator
- Emulators
 - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
 - MPLAB ICD 3
 - PICKit™ 3
- Device Programmers
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards,
Evaluation Kits and Starter Kits
- Third-party development tools

29.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

TABLE 30-12: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO10	VOL	Output Low Voltage 4x Sink Driver Pins ⁽²⁾	—	—	0.4	V	VDD = 3.3V, IOL ≤ 6 mA, -40°C ≤ TA ≤ +85°C IOL ≤ 5 mA, +85°C < TA ≤ +125°C
		Output Low Voltage 8x Sink Driver Pins ⁽³⁾	—	—	0.4	V	VDD = 3.3V, IOL ≤ 12 mA, -40°C ≤ TA ≤ +85°C IOL ≤ 8 mA, +85°C < TA ≤ +125°C
DO20	VOH	Output High Voltage 4x Source Driver Pins ⁽²⁾	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V
		Output High Voltage 8x Source Driver Pins ⁽³⁾	2.4	—	—	V	IOH ≥ -15 mA, VDD = 3.3V
DO20A	VOH1	Output High Voltage 4x Source Driver Pins ⁽²⁾	1.5 ⁽¹⁾	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0 ⁽¹⁾	—	—		IOH ≥ -12 mA, VDD = 3.3V
			3.0 ⁽¹⁾	—	—		IOH ≥ -7 mA, VDD = 3.3V
		Output High Voltage 8x Source Driver Pins ⁽³⁾	1.5 ⁽¹⁾	—	—	V	IOH ≥ -22 mA, VDD = 3.3V
			2.0 ⁽¹⁾	—	—		IOH ≥ -18 mA, VDD = 3.3V
			3.0 ⁽¹⁾	—	—		IOH ≥ -10 mA, VDD = 3.3V

Note 1: Parameters are characterized but not tested.

2: Includes all I/O pins that are not 8x Sink Driver pins (see below).

3: Includes the following pins:

For devices with less than 64 pins: RA3, RA4, RA9, RB<7:15> and RC3

For 64-pin devices: RA4, RA9, RB<7:15>, RC3 and RC15

TABLE 30-13: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min. ⁽²⁾	Typ.	Max.	Units	Conditions
BO10	VBOR	BOR Event on VDD Transition High-to-Low	2.65	—	2.95	V	VDD (Notes 2 and 3)

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance.

2: Parameters are for design guidance only and are not tested in manufacturing.

3: The VBOR specification is relative to VDD.

FIGURE 30-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS

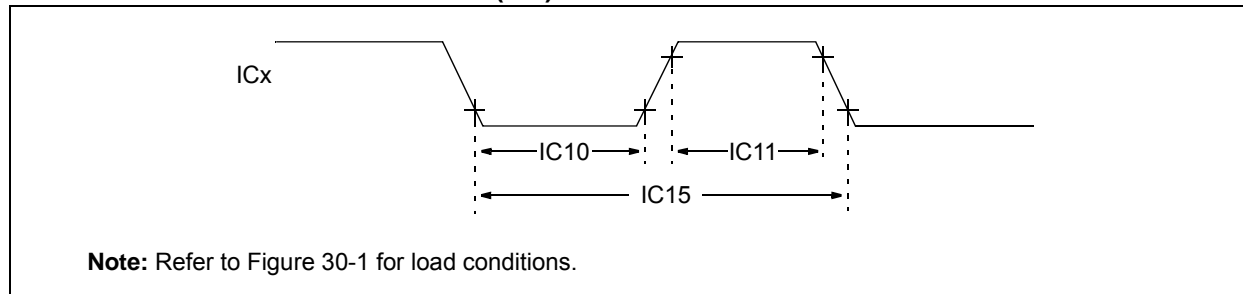


TABLE 30-26: INPUT CAPTURE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Max.	Units	Conditions	
IC10	TccL	ICx Input Low Time	Greater of 12.5 + 25 or (0.5 Tcy/N) + 25	—	ns	Must also meet Parameter IC15	N = prescale value (1, 4, 16)
IC11	TccH	ICx Input High Time	Greater of 12.5 + 25 or (0.5 Tcy/N) + 25	—	ns	Must also meet Parameter IC15	
IC15	TccP	ICx Input Period	Greater of 25 + 50 or (1 Tcy/N) + 50	—	ns		

Note 1: These parameters are characterized, but not tested in manufacturing.

TABLE 30-33: SPI2 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended			
Maximum Data Rate	Master Transmit Only (Half-Duplex)	Master Transmit/Receive (Full-Duplex)	Slave Transmit/Receive (Full-Duplex)	CKE	CKP	SMP
15 MHz	Table 30-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 30-34	—	1	0,1	1
9 MHz	—	Table 30-35	—	0	0,1	1
15 MHz	—	—	Table 30-36	1	0	0
11 MHz	—	—	Table 30-37	1	1	0
15 MHz	—	—	Table 30-38	0	1	0
11 MHz	—	—	Table 30-39	0	0	0

FIGURE 30-14: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0)
TIMING CHARACTERISTICS

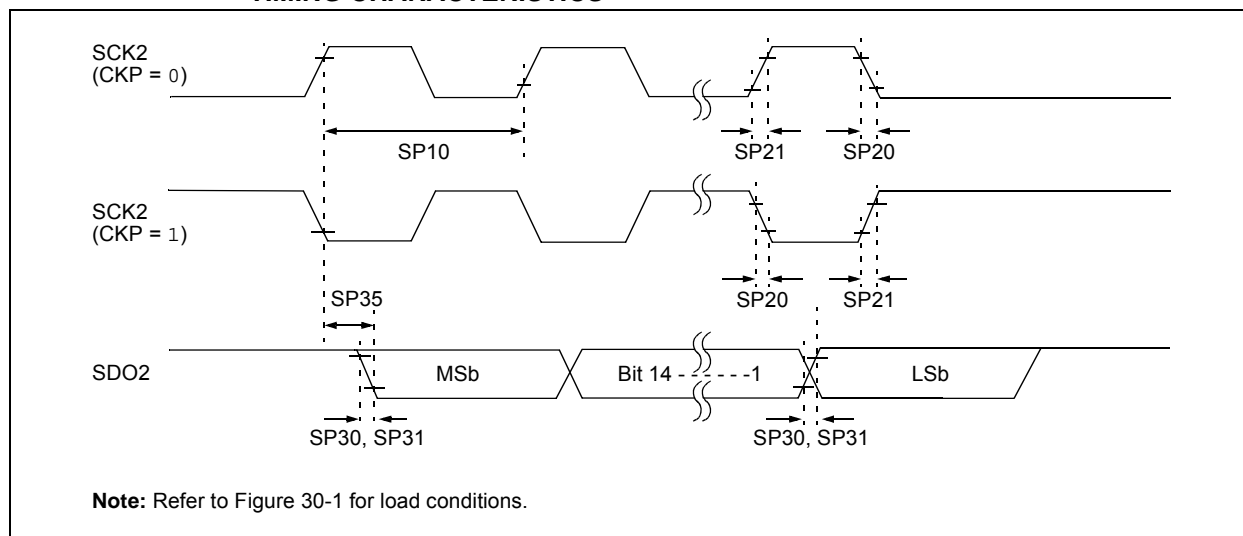


TABLE 30-56: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
CTMU Current Source							
CTMUI1	IOUT1	Base Range ⁽¹⁾	0.29	—	0.77	μA	CTMUICON<9:8> = 01
CTMUI2	IOUT2	10x Range ⁽¹⁾	3.85	—	7.7	μA	CTMUICON<9:8> = 10
CTMUI3	IOUT3	100x Range ⁽¹⁾	38.5	—	77	μA	CTMUICON<9:8> = 11
CTMUI4	IOUT4	1000x Range ⁽¹⁾	385	—	770	μA	CTMUICON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage ^(1,2)	—	0.598	—	V	T _A = +25°C, CTMUICON<9:8> = 01
			—	0.658	—	V	T _A = +25°C, CTMUICON<9:8> = 10
			—	0.721	—	V	T _A = +25°C, CTMUICON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change ^(1,2,3)	—	-1.92	—	mV/°C	CTMUICON<9:8> = 01
			—	-1.74	—	mV/°C	CTMUICON<9:8> = 10
			—	-1.56	—	mV/°C	CTMUICON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUICON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing.

3: Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC configured for 10-bit mode
- ADC module configured for conversion speed of 500 ksp/s
- All PMDx bits are cleared (PMDx = 0)
- Executing a while(1) statement
- Device operating from the FRC with no PLL

Revision C (December 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

In addition, where applicable, new sections were added to each peripheral chapter that provide information and links to related resources, as well as helpful tips. For examples, see **Section 20.1 “UART Helpful Tips”** and **Section 3.6 “CPU Resources”**.

All occurrences of TLA were updated to VTLA throughout the document, with the exception of the pin diagrams (updated diagrams were not available at time of publication).

A new chapter, **Section 31.0 “DC and AC Device Characteristics Graphs”**, was added.

All other major changes are referenced by their respective section in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
“16-bit Microcontrollers and Digital Signal Controllers (up to 256-Kbyte Flash and 32-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog”	The content on the first page of this section was extensively reworked to provide the reader with the key features and functionality of this device family in an “at-a-glance” format.
Section 1.0 “Device Overview”	Updated the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X Block Diagram (see Figure 1-1), which now contains a CPU block and a reference to the CPU diagram. Updated the description and Note references in the Pinout I/O Descriptions for these pins: C1IN2-, C2IN2-, C3IN2-, OA1OUT, OA2OUT, and OA3OUT (see Table 1-1).
Section 2.0 “Guidelines for Getting Started with 16-bit Digital Signal Controllers and Microcontrollers”	Updated the Recommended Minimum Connection diagram (see Figure 2-1).
Section 3.0 “CPU”	Updated the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X CPU Block Diagram (see Figure 3-1). Updated the Status register definition in the Programmer’s Model (see Figure 3-2).
Section 4.0 “Memory Organization”	Updated the Data Memory Maps (see Figure 4-6 and Figure 4-11). Removed the DCB<1:0> bits from the OC1CON2, OC2CON2, OC3CON2, and OC4CON2 registers in the Output Compare 1 Through Output Compare 4 Register Map (see Table 4-10). Added the TRIG1 and TRGCON1 registers to the PWM Generator 1 Register Map (see Table 4-13). Added the TRIG2 and TRGCON2 registers to the PWM Generator 2 Register Map (see Table 4-14). Added the TRIG3 and TRGCON3 registers to the PWM Generator 3 Register Map (see Table 4-15). Updated the second note in Section 4.7.1 “Bit-Reversed Addressing Implementation” .
Section 8.0 “Direct Memory Access (DMA)”	Updated the DMA Controller diagram (see Figure 8-1).
Section 14.0 “Input Capture”	Updated the bit values for the ICx clock source of the ICTSEL<12:10> bits in the ICxCON1 register (see Register 14-1).
Section 15.0 “Output Compare”	Updated the bit values for the OCx clock source of the OCTSEL<2:0> bits in the OCxCON1 register (see Register 15-1). Removed the DCB<1:0> bits from the Output Compare x Control Register 2 (see Register 15-2).

TABLE A-5: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 “Electrical Characteristics”	<ul style="list-style-type: none"> • Throughout: qualifies all footnotes relating to the operation of analog modules below VDDMIN (replaces “will have” with “may have”) • Throughout: changes all references of SPI timing parameter symbol “TscP” to “FscP” • Table 30-1: changes VDD range to 3.0V to 3.6V • Table 30-4: removes Parameter DC12 (RAM Retention Voltage) • Table 30-7: updates Maximum values at 10 and 20 MIPS • Table 30-8: adds Maximum IPD values, and removes all ΔI_{WDT} entries • Adds new Table 30-9 (Watchdog Timer Delta Current) with consolidated values removed from Table 30-8. All subsequent tables are renumbered accordingly. • Table 30-10: adds footnote for all parameters for 1:2 Doze ratio • Table 30-11: <ul style="list-style-type: none"> - changes Minimum and Maximum values for D120 and D130 - adds Minimum and Maximum values for D131 - adds Minimum and Maximum values for D150 through D156, and removes Typical values • Table 30-12: <ul style="list-style-type: none"> - reformats table for readability - changes IOL conditions for DO10 • Table 30-14: adds footnote to D135 • Table 30-17: changes Minimum and Maximum values for OS30 • Table 30-19: <ul style="list-style-type: none"> - splits temperature range and adds new values for F20a - reduces temperature range for F20b to extended temperatures only • Table 30-20: <ul style="list-style-type: none"> - splits temperature range and adds new values for F21a - reduces temperature range for F20b to extended temperatures only • Table 30-53: <ul style="list-style-type: none"> - adds Maximum value to CM30 - adds footnote (“Parameter characterized...”) to multiple parameters • Table 30-55: adds Minimum and Maximum values for all CTMUI specifications, and removes Typical values • Table 30-57: adds new footnote to AD09 • Table 30-58: <ul style="list-style-type: none"> - removes all specifications for accuracy with external voltage references - removes Typical values for AD23a and AD24a - replaces Minimum and Maximum values for AD21a, AD22a, AD23a and AD24a with new values, split by Industrial and Extended temperatures - removes Maximum value of AD30 - removes Minimum values from AD31a and AD32a - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-59: <ul style="list-style-type: none"> - removes all specifications for accuracy with external voltage references - removes Maximum value of AD30 - removes Typical values for AD23b and AD24b - replaces Minimum and Maximum values for AD21b, AD22b, AD23b and AD24b with new values, split by Industrial and Extended temperatures - removes Minimum and Maximum values from AD31b, AD32b, AD33b and AD34b - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-61: Adds footnote to AD51
Section 32.0 “DC and AC Device Characteristics Graphs”	<ul style="list-style-type: none"> • Updates Figure 32-6 (Typical IDD @ 3.3V) with individual current vs. processor speed curves for the different program memory sizes
Section 33.0 “Packaging Information”	<ul style="list-style-type: none"> • Replaces drawing C04-149C (64-pin QFN, 7.15 x 7.15 exposed pad) with C04-154A (64-pin QFN, 5.4 x 5.4 exposed pad)